

TrilithIC

BTS 7750 G

Data Sheet

1 Overview

1.1 Features

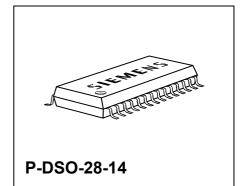
- Quad D-MOS switch driver
- Free configurable as bridge or quad-switch
- Optimized for DC motor management applications
- Low R_{DS ON}: 70 mΩ high-side switch, 45 mΩ lowside switch (typical values @ 25 °C)
- Maximum peak current: typ. 12 A @ 25 ℃
- Very low quiescent current: typ. 5 μA @ 25 $^{\circ}\!C$
- Small outline, enhanced power P-DSO-package
- Full short-circuit-protection
- Operates up to 40 V
- Status flag diagnosis
- · Overtemperature shut down with hysteresis
- Internal clamp diodes
- · Isolated sources for external current sensing
- · Under-voltage detection with hysteresis
- PWM frequencies up to 1 kHz

| Туре | Ordering Code | Package |
|------------|---------------|-------------|
| BTS 7750 G | Q67007-A9401 | P-DSO-28-14 |

1.2 Description

The **BTS 7750 G** is part of the **TrilithIC** family containing three dies in one package: One double high-side switch and two low-side switches. The drains of these three vertical DMOS chips are mounted on separated leadframes. The sources are connected to individual pins, so the **BTS 7750 G** can be used in H-bridge- as well as in any other configuration. Both the double high-side and the two low-side switches of the **BTS 7750 G** are manufactured in **SMART SIPMOS**[®] technology which combines low $R_{DS ON}$ vertical DMOS power stages with CMOS control circuitry. The high-side switch is fully protected and contains the control and diagnosis circuitry. Also the low-side switches are fully protected, the equivalent standard product is the **BSP 78**.

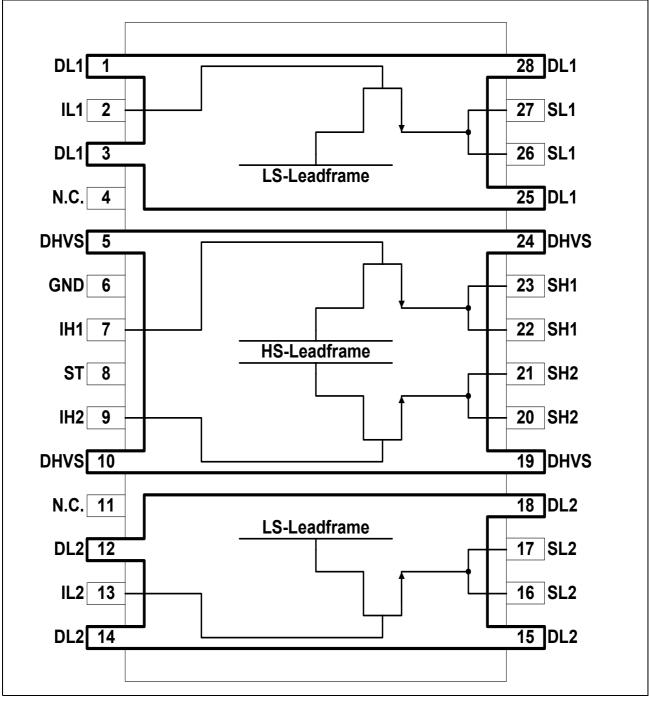
In contrast to the **BTS 7750 GP**, which consists of the same chips in an **P-TO263-15** package, the **P-DSO-28-14** package offers a smaller outline and a lower price for applications, which do not need the thermal properties of the **P-TO263-15**.





1.3 Pin Configuration

(top view)









| Pin No. | Symbol | Function |
|----------------|--------|---------------------------------------------------------------------------------|
| 1, 3, 25, 28 | DL1 | Drain of low-side switch1, leadframe 1 ¹⁾ |
| 2 | IL1 | Analog input of low-side switch1 |
| 4 | N.C. | not connected |
| 5, 10, 19, 24 | DHVS | Drain of high-side switches and power supply voltage, leadframe 2 ¹⁾ |
| 6 | GND | Ground |
| 7 | IH1 | Digital input of high-side switch1 |
| 8 | ST | Status of high-side switches; open Drain output |
| 9 | IH2 | Digital input of high-side switch2 |
| 11 | N.C. | not connected |
| 12, 14, 15, 18 | DL2 | Drain of low-side switch2, leadframe 3 ¹⁾ |
| 13 | IL2 | Analog input of low-side switch2 |
| 16,17 | SL2 | Source of low-side switch2 |
| 20,21 | SH2 | Source of high-side switch2 |
| 22,23 | SH1 | Source of high-side switch1 |
| 26,27 | SL1 | Source of low-side switch1 |

1.4 Pin Definitions and Functions

¹⁾ To reduce the thermal resistance these pins are direct connected via metal bridges to the leadframe.

Pins written in **bold type** need power wiring.



1.5 Functional Block Diagram

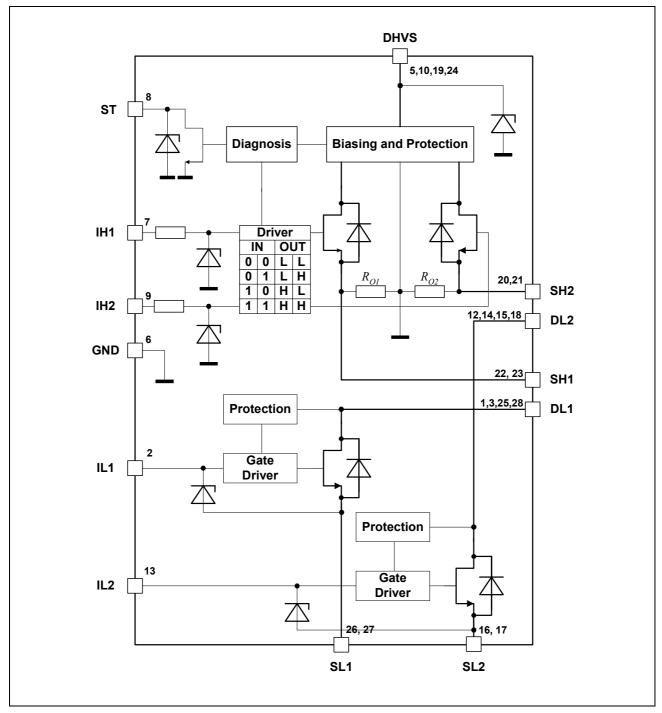


Figure 2 Block Diagram



1.6 Circuit Description

Input Circuit

The control inputs IH1,2 consist of TTL/CMOS compatible Schmitt-Triggers with hysteresis. Buffer amplifiers are driven by these stages and convert the logic signal into the necessary form for driving the power output stages. The inputs are protected by ESD clamp-diodes.

The inputs IL1 and IL2 are connected to the internal gate-driving units of the N-channel vertical power-MOS-FETs.

Output Stages

The output stages consist of an low $R_{\text{DS ON}}$ Power-MOS H-bridge. In H-bridge configuration, the D-MOS body diodes can be used for freewheeling when commutating inductive loads. If the high-side switches are used as single switches, positive and negative voltage spikes which occur when driving inductive loads are limited by integrated power clamp diodes.

Short Circuit Protection

The outputs are protected against

- output short circuit to ground
- output short circuit to the supply voltage, and
- overload (load short circuit).

An internal OP-Amp controls the Drain-Source-Voltage by comparing the DS-Voltage-Drop with an internal reference voltage. Above this trippoint the OP-Amp reduces the output current depending on the junction temperature and the drop voltage.

In the case of overloaded high-side switches the status output is set to low.

The fully protected low-side switches have no status output.

Overtemperature Protection

The high-side and the low-side switches also incorporate an overtemperature protection circuit with hysteresis which switches off the output transistors. In the case of the high-side switches, the status output is set to low.

Undervoltage-Lockout (UVLO)

When $V_{\rm S}$ reaches the switch-on voltage $V_{\rm UVON}$ the IC becomes active with a hysteresis. The High-Side output transistors are switched off if the supply voltage $V_{\rm S}$ drops below the switch off value $V_{\rm UVOFF}$.



Status Flag

The status flag output is an open drain output with Zener-diode which requires a pull-up resistor, c.f. the application circuit on page 14. Various errors as listed in the table "Diagnosis" are detected by switching the open drain output ST to low. A open load detection is not available. Freewheeling condition does not cause an error.

2 Truthtable and Diagnosis (valid only for the High-Side-Switches)

| Flag | IH1 | IH2 | SH1 | SH2 | ST | Remarks |
|-----------------------------------------|-----|------|-----|-------|----|----------------------|
| | In | puts | Ou | tputs | | |
| | 0 | 0 | L | L | 1 | stand-by mode |
| Normal operation; | 0 | 1 | L | Н | 1 | switch2 active |
| identical with functional truth table | 1 | 0 | н | L | 1 | switch1 active |
| | 1 | 1 | Н | Н | 1 | both switches active |
| Overtemperature high-side switch1 | 0 | Х | L | Х | 1 | |
| | 1 | Х | L | Х | 0 | detected |
| Overtemperature high-side switch2 | Х | 0 | Х | L | 1 | |
| | Х | 1 | Х | L | 0 | detected |
| Overtemperature both high-side switches | 0 | 0 | L | L | 1 | |
| | X | 1 | L | L | 0 | detected |
| | 1 | Х | L | L | 0 | detected |
| Undervoltage | Х | Х | L | L | 1 | not detected |

Inputs:

0 = Logic LOW

1 = Logic HIGH

X = don't care

Outputs:

Z = Output in tristate condition

L = Output in sink condition

H = Output in source condition

X = Voltage level undefined

Status: 1 = No error 0 = Error





3 Electrical Characteristics

3.1 Absolute Maximum Ratings

– 40 °C < *T*_j < 150 °C

| Parameter | Symbol | Limit | Values | Unit | Remarks |
|-----------|--------|-------|--------|------|---------|
| | | min. | max. | | |

High-Side-Switches (Pins DHVS, IH1,2 and SH1,2)

| Supply voltage | Vs | - 0.3 | 42 | V | - |
|--------------------------------------------------|-------------------|-------|----|----|------------------------------------|
| Supply voltage for full short circuit protection | $V_{\rm S(SCP)}$ | | 28 | V | |
| HS-drain current* | Is | - 7.5 | ** | А | $T_{\rm A}$ = 25°C; t_P < 100 ms |
| HS-input current | I _{IH} | - 5 | 5 | mA | Pin IH1 and IH2 |
| HS-input voltage | V_{IH} | - 10 | 16 | V | Pin IH1 and IH2 |

Note: * single pulse ** internally limited

Status Output ST

| Status pull up voltage | V _{ST} | - 0.3 | 5.4 | V | |
|------------------------|-----------------|-------|-----|----|--------|
| Status Output current | $I_{\rm ST}$ | - 5 | 5 | mA | Pin ST |

Low-Side-Switches (Pins DL1,2, IL1,2 and SL1,2)

| Drain-Source-Clamp voltage | $V_{\rm DSL}$ | 42 | _ | V | $V_{\rm IL}$ = 0 V; $I_{\rm D} \le$ 1 mA |
|----------------------------|--------------------|-------|----|---|------------------------------------------|
| Supply voltage for short | $V_{\rm DSL(SCP)}$ | | 30 | V | $V_{\rm IL}$ = 5 V |
| circuit protection | | | 20 | V | <i>V</i> _{IL} = 10 V |
| LS-drain current* | $I_{\rm DL}$ | - 7.5 | ** | А | $T_{\rm A}$ = 25°C; t_P < 100 ms |
| LS-input voltage | V_{IL} | - 0.3 | 10 | V | - |

Note: * single pulse ** internally limited

Temperatures

| Junction temperature | Tj | - 40 | 150 | °C | - |
|----------------------|--------------|------|-----|----|---|
| Storage temperature | $T_{ m stg}$ | - 55 | 150 | °C | - |



3.1 Absolute Maximum Ratings (cont'd)

– 40 °C < *T*i < 150 °C

| Parameter | Symbol | Limit Values | | Unit | Remarks |
|-----------|--------|--------------|------|------|---------|
| | | min. | max. | | |

Thermal Resistances (one HS-LS-Path active)

| LS-junction case | $R_{ m thjC\ L}$ | _ | 20 | K/W | measured to pin 3 or 12 |
|----------------------------------------------------------------|------------------|---|----|-----|----------------------------------------------------------------------------|
| HS-junction case | $R_{ m thjC~H}$ | - | 20 | K/W | measured to pin 19 |
| Junction ambient $R_{thja} = T_{j(HS)}/(P_{(HS)}+P_{(LS)})$ | $R_{ m thja}$ | _ | 60 | K/W | device soldered to reference PCB with 6 cm ² cooling area |

ESD Protection (Human Body Model acc. MIL STD 883D, method 3015.7 and EOS/ ESD assn. standard S5.1 - 1993)

| Input LS-Switch | $V_{\rm ESD}$ | _ | 2 | kV | |
|-------------------------|---------------|---|---|----|------------------------------------|
| Input HS-Switch | $V_{\rm ESD}$ | - | 1 | kV | |
| Status HS-Switch | $V_{\rm ESD}$ | - | 2 | kV | |
| Output LS and HS-Switch | $V_{\rm ESD}$ | - | 8 | kV | all other pins connected to Ground |

Note: Maximum ratings are absolute ratings; exceeding any one of these values may cause irreversible damage to the integrated circuit.

3.2 Operating Range

 $-40 \circ C < T_i < 150 \circ C$

| Parameter | Symbol | Symbol Limit Va | | | Remarks | |
|----------------------|-----------------|-----------------|------|----|-----------------------------------------------|--|
| | | min. | max. | | | |
| Supply voltage | Vs | $V_{\rm UVOFF}$ | 42 | V | After $V_{\rm S}$ rising above $V_{\rm UVON}$ | |
| Input voltages | V _{IH} | - 0.3 | 15 | V | - | |
| Input voltages | V _{IL} | - 0.3 | 10 | V | - | |
| Output current | I _{ST} | 0 | 2 | mA | - | |
| Junction temperature | Tj | - 40 | 150 | °C | - | |

Note: In the operating range the functions given in the circuit description are fulfilled.



3.3 Electrical Characteristics

 $I_{\rm SH1}$ = $I_{\rm SH2}$ = $I_{\rm SL1}$ = $I_{\rm SL2}$ = 0 A; – 40 °C < $T_{\rm j}$ < 150 °C; 8 V < $V_{\rm S}$ < 18 V unless otherwise specified

| Parameter | Symbol | Limit Values | | | Unit | Test Condition |
|-----------|--------|--------------|------|------|------|----------------|
| | | min. | typ. | max. | | |

Current Consumption HS-switch

| Quiescent current | Is | - | 5 | 8 | μA | IH1 = IH2 = 0 V T _j = 25 °C |
|--------------------------------------------------------------------|------------------------------------------|---|-----|-----|----|-------------------------------------------|
| | | _ | - | 12 | μA | IH1 = IH2 = 0 V |
| Supply current | Is | - | 1.5 | 2.6 | mA | IH1 or IH2 = 5 V V _s = 12 V |
| | | - | 3 | 5.2 | mA | IH1 and IH2 = 5 V $V_{\rm S}$ = 12 V |
| Leakage current of highside switch | I _{sh lk} | - | - | 6 | μA | $V_{\rm IH}$ = $V_{\rm SH}$ = 0 V |
| Leakage current through logic GND in free wheeling condition | $I_{\rm LKCL} = I_{\rm FH} + I_{\rm SH}$ | - | _ | 10 | mA | <i>I</i> _{FH} = 3 А |

Current Consumption LS-switch

| Input current | I _{IL} | _ | 8 | 30 | μA | $V_{\rm IL}$ = 5 V; normal operation |
|-----------------------------------|-----------------|---|-----|-----|----|-----------------------------------------|
| | | _ | 160 | 300 | μA | $V_{\rm IL}$ = 5 V; failure mode |
| Leakage current of lowside switch | $I_{\rm DLLK}$ | _ | 2 | 10 | μA | $V_{\rm IL} = 0 V$ |

Under Voltage Lockout (UVLO) HS-switch

| Switch-ON voltage | $V_{\rm UVON}$ | _ | _ | 4.5 | V | $V_{\rm S}$ increasing |
|--------------------------|-----------------|-----|---|-----|---|--------------------------------|
| Switch-OFF voltage | $V_{\rm UVOFF}$ | 1.8 | - | 3.2 | V | $V_{\rm S}$ decreasing |
| Switch ON/OFF hysteresis | $V_{\rm UVHY}$ | - | 1 | - | V | $V_{\rm UVON} - V_{\rm UVOFF}$ |



3.3 Electrical Characteristics (cont'd)

 I_{SH1} = I_{SH2} = I_{SL1} = I_{SL2} = 0 A; – 40 °C < T_j < 150 °C; 8 V < V_S < 18 V unless otherwise specified

| Parameter | Symbol | Limit Values | | | Unit | Test Condition |
|-----------|--------|--------------|------|------|------|----------------|
| | | min. | typ. | max. | | |

Output stages

| Inverse diode of high-side switch; Forward-voltage | V_{FH} | _ | 0.8 | 1.2 | V | I _{FH} = 3 А |
|------------------------------------------------------------|----------------------|---|-----|-----|----|---------------------------------------------------------------------------------------------------------|
| Inverse diode of lowside switch; Forward-voltage | V_{FL} | _ | 0.8 | 1.2 | V | <i>I</i> _{FL} = 3 A |
| Static drain-source on-resistance of highside switch | R _{DS ON H} | _ | 70 | 90 | mΩ | <i>I</i> _{SH} = 1 A <i>T</i> _j = 25 °C |
| Static drain-source on-resistance of lowside switch | R _{DS ON L} | _ | 45 | 60 | mΩ | I_{SL} = 1 A; V_{GL} = 5 V T_{j} = 25 °C |
| Static path on-resistance | $R_{\rm DS \ ON}$ | - | - | 285 | mΩ | $\begin{aligned} R_{\text{DS ON H}} + R_{\text{DS ON L}} \\ I_{\text{SH}} = 1 \text{ A}; \end{aligned}$ |

Short Circuit of highside switch to GND

| Initial peak SC current | I _{SCP H} | 14 | 15 | 18 | А | <i>T</i> _j = − 40 °C |
|-------------------------|--------------------|----|-----|----|---|----------------------------------|
| | | 10 | 12 | 15 | А | <i>T</i> _j = + 25 °C |
| | | 7 | 8.5 | 10 | А | <i>T</i> _j = + 150 °C |

Short Circuit of highside switch to V_s

| Output pull-down-resistor | R _o | 8 | 15 | 35 | kΩ | $V_{\rm DSL}$ = 3 V |
|---------------------------|----------------|---|----|----|----|---------------------|
|---------------------------|----------------|---|----|----|----|---------------------|

Short Circuit of lowside switch to V_s

| Initial peak SC current | ISCPL | 21 | 28 | 34 | А | <i>T</i> _j = − 40 °C |
|-------------------------|-------|----|----|----|---|---------------------------------|
| | | 16 | 22 | 27 | А | <i>T</i> _j = 25 °C |
| | | 11 | 14 | 18 | А | <i>T</i> _j = 150 °C |



3.3 Electrical Characteristics (cont'd)

 $I_{SH1} = I_{SH2} = I_{SL1} = I_{SL2} = 0 \text{ A}; -40 \text{ °C} < T_j < 150 \text{ °C}; 8 \text{ V} < V_S < 18 \text{ V}$ unless otherwise specified

| Parameter | Symbol | Limit Values | | | Unit | Test Condition |
|-----------|--------|--------------|------|------|------|----------------|
| | | min. | typ. | max. | | |

Thermal Shutdown

| Thermal shutdown junction temperature | $T_{\rm jSD}$ | 155 | 180 | 190 | °C | _ |
|----------------------------------------|-------------------|-----|-----|-----|----|----------------------------------------|
| Thermal switch-on junction temperature | T _{j SO} | 150 | 170 | 180 | °C | _ |
| Temperature hysteresis | ΔT | I | 10 | _ | °C | $\Delta T = T_{\rm jSD} - T_{\rm jSO}$ |

Status Flag Output ST of highside switch

| Low output voltage | V _{ST L} | _ | 0.2 | 0.6 | V | <i>I</i> _{ST} = 1.6 mA |
|---------------------|-------------------|-----|-----|-----|----|---------------------------------|
| Leakage current | $I_{\rm STLK}$ | - | - | 10 | μA | $V_{\rm ST}$ = 5 V |
| Zener-limit-voltage | V _{ST Z} | 5.4 | | - | V | <i>I</i> _{ST} = 1.6 mA |

Switching times of highside switch

| Turn-ON-time; to 90% $V_{\rm SH}$ | t _{on} | _ | 85 | 180 | μS | R_{Load} = 12 Ω V_{s} = 12 V |
|------------------------------------------|----------------------------|---|----|-----|------|--------------------------------------------|
| Turn-OFF-time; to 10% V _{SH} | t _{off} | _ | 80 | 180 | μS | R_{Load} = 12 Ω V_{s} = 12 V |
| Slew rate on 10 to 30% $V_{\rm SH}$ | <i>dV/dt</i> _{ON} | _ | _ | 1.1 | V/µs | R_{Load} = 12 Ω V_{s} = 12 V |
| Slew rate off 70 to 40% $V_{\rm SH}$ | -dV/ dt _{OFF} | _ | _ | 1.5 | V/µs | R_{Load} = 12 Ω V_{S} = 12 V |

Note: switching times are guaranteed by design



3.3 Electrical Characteristics (cont'd)

 $I_{SH1} = I_{SH2} = I_{SL1} = I_{SL2} = 0 \text{ A}; -40 \text{ °C} < T_j < 150 \text{ °C}; 8 \text{ V} < V_S < 18 \text{ V}$ unless otherwise specified

| Parameter | Symbol | Limit Values | | Unit | Test Condition | |
|-----------|--------|--------------|------|------|----------------|--|
| | | min. | typ. | max. | | |

Switching times of lowside switch

| Turn-ON-time 70 to 50% $V_{SH}V_{IL}$ = 0 to 10 V | t _{on} | _ | 70 | 170 | μS | R_{Load} = 12 Ω V_{s} = 12 V |
|------------------------------------------------------------------|----------------------|---|----|-----|------|--------------------------------------------|
| Turn-OFF-time; to 10% V _{SL} | t _{OFF} | _ | 40 | 150 | μS | R_{Load} = 12 Ω V_{s} = 12 V |
| Slew rate on 70 to 50% $V_{\rm SH}$ $V_{\rm IL}$ = 0 to 10 V | -dV/dt _{on} | _ | _ | 1.0 | V/µs | R_{Load} = 12 Ω V_{s} = 12 V |
| Slew rate off 50 to 70% $V_{\rm SH}$ $V_{\rm IL}$ = 0 to 10 V | dV/dt_{OFF} | — | _ | 1.0 | V/µs | R_{Load} = 12 Ω V_{s} = 12 V |

Note: switching times are guaranteed by design

Control Inputs of highside switches GH 1, 2

| H-input voltage | $V_{\rm IH\ High}$ | _ | _ | 2.5 | V | - |
|-------------------------|--------------------|-----|-----|-----|----|--------------------------|
| L-input voltage | $V_{\rm IH\ Low}$ | 1 | _ | _ | V | - |
| Input voltage hysterese | V _{IH HY} | _ | 0.3 | _ | V | - |
| H-input current | $I_{IH\ High}$ | 15 | 30 | 60 | μA | V _{IH} = 5 V |
| L-input current | $I_{IH \ Low}$ | 5 | - | 20 | μA | V _{IH} = 0.4 V |
| Input series resistance | R_{I} | 2.7 | 4 | 5.5 | kΩ | - |
| Zener limit voltage | V _{IH Z} | 5.4 | _ | _ | V | I _{IH} = 1.6 mA |

Control Inputs GL1, 2

| Gate-threshold-voltage | $V_{\rm IL\ th}$ | 0.9 | 1.7 | 2.2 | V | $I_{\rm DL}$ = 2 mA |
|------------------------|------------------|-----|-----|-----|---|---------------------|
|------------------------|------------------|-----|-----|-----|---|---------------------|

Note: The listed characteristics are ensured over the operating range of the integrated circuit. Typical characteristics specify mean values expected over the production spread. If not otherwise specified, typical characteristics apply at T_A = 25°C and the given supply voltage.



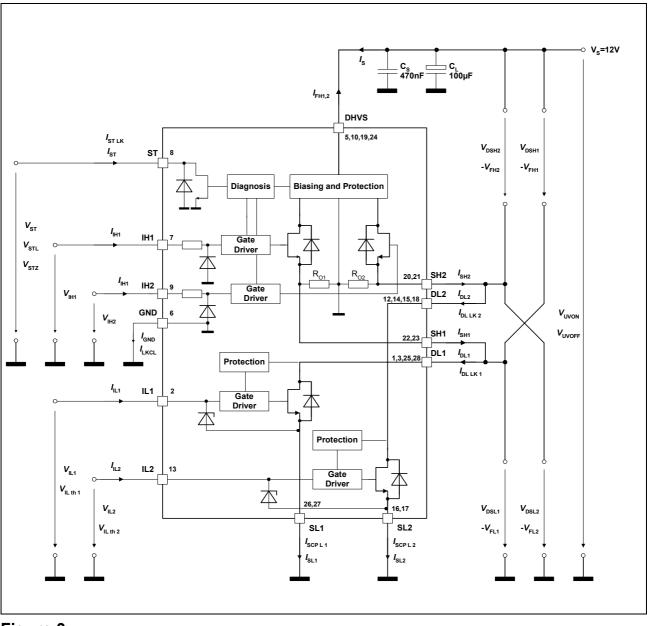


Figure 3 Test Circuit

| HS-Source-Current | Named during Short Circuit | Named during Leakage- Cond. |
|--------------------|-------------------------------|--------------------------------|
| I _{SH1,2} | I _{SCP H} | I _{dl lk} |



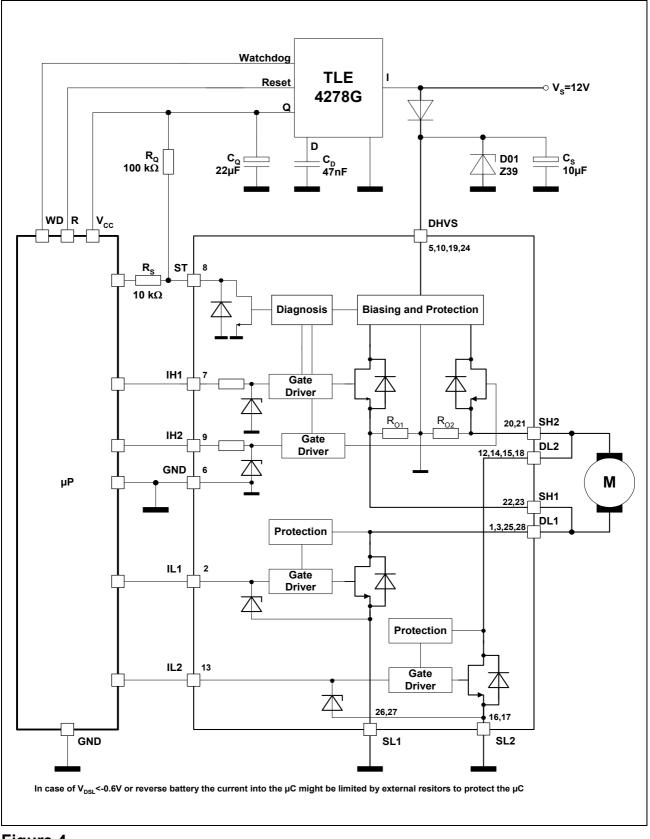
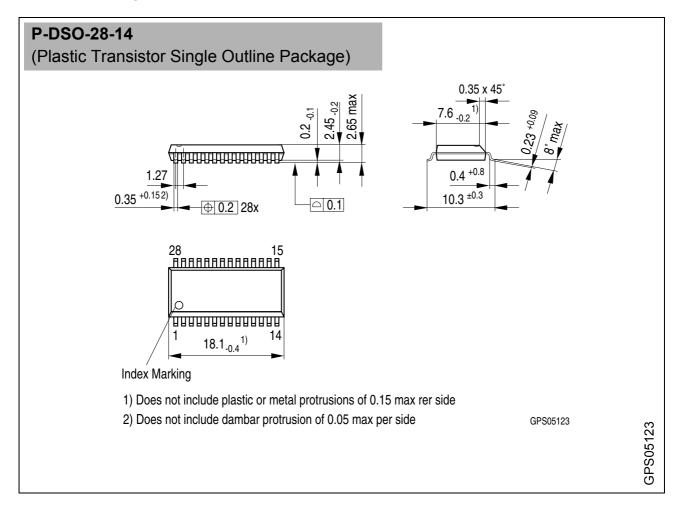


Figure 4 Application Circuit



4 Package Outlines



Sorts of Packing Package outlines for tubes, trays etc. are contained in our Data Book "Package Information". SMD = Surface Mounted Device

Dimensions in mm



Published by Infineon Technologies AG i Gr., Bereichs Kommunikation St.-Martin-Strasse 53, D-81541 München © Infineon Technologies AG 1999 All Rights Reserved.

Attention please!

The information herein is given to describe certain components and shall not be considered as warranted characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Infineon Technologies is an approved CECC manufacturer.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office in Germany or our Infineon Technologies Representatives worldwide (see address list).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.